

Title (en)
APPARATUS AND PROCESS FOR TREATING DIELECTRIC MATERIALS

Title (de)
VORRICHTUNG UND PROZESS ZUM BEHANDELN VON DIELEKTRISCHEN MATERIALIEN

Title (fr)
DISPOSITIF ET PROCEDE DE TRAITMENT DES MATERIAUX DIELECTRIQUES

Publication
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Application
EP 05763782 A 20050622

Priority
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Abstract (en)
[origin: WO2007001281A1] Apparatuses and processes for treating dielectric materials such as low k dielectric materials, premetal dielectric materials, barrier layers, and the like, generally comprise a radiation source module, a process chamber module coupled to the radiation source module; and a loadlock chamber module in operative communication with the process chamber and a wafer handler. The atmosphere of each one of the modules can be controlled as may be desired for different types of dielectric materials. The radiation source module includes a reflector, an ultraviolet radiation source, and a plate transmissive to the wavelengths of about 150 nm to about 300 nm, to define a sealed interior region, wherein the sealed interior region is in fluid communication with a fluid source.

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